

BUK7108-40AIE

N-channel TrenchPLUS standard level FET

Rev. 03 — 19 February 2009

Product data sheet

1. Product profile

1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. The devices include TrenchPLUS current sensing and diodes for ElectroStatic Discharge (ESD) protection. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- Electrostatically robust due to integrated protection diodes
- Low conduction losses due to low on-state resistance
- Q101 compliant
- Reduced component count due to integrated current sensor
- Suitable for standard level gate drive sources

1.3 Applications

- Electrical Power Assisted Steering (EPAS)
- Variable Valve Timing for engines

1.4 Quick reference data

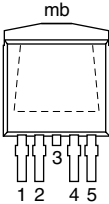
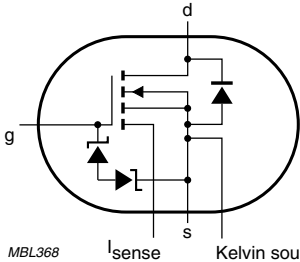
Table 1. Quick reference

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$	-	-	40	V
I_D	drain current	$V_{GS} = 10\text{ V}$; $T_{mb} = 25\text{ °C}$; see Figure 2 ; see Figure 3 ;	[1]	-	117	A
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 50\text{ A}$; $T_j = 25\text{ °C}$; see Figure 7 ; see Figure 8	-	6	8	mΩ
I_D/I_{sense}	ratio of drain current to sense current	$T_j > -55\text{ °C}$; $T_j < 175\text{ °C}$; $V_{GS} > 10\text{ V}$	450	500	550	

[1] Current is limited by power dissipation chip rating.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 SOT426 (D2PAK)	 <i>MBL368</i>
2	ISENSE	sense current		
3	D	drain		
4	KS	Kelvin source		
5	S	source		
mb	D	mounting base; connected to drain		

3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BUK7108-40AIE	D2PAK	plastic single-ended surface-mounted package (D2PAK); 5 leads (one lead cropped)	SOT426

4. Limiting values

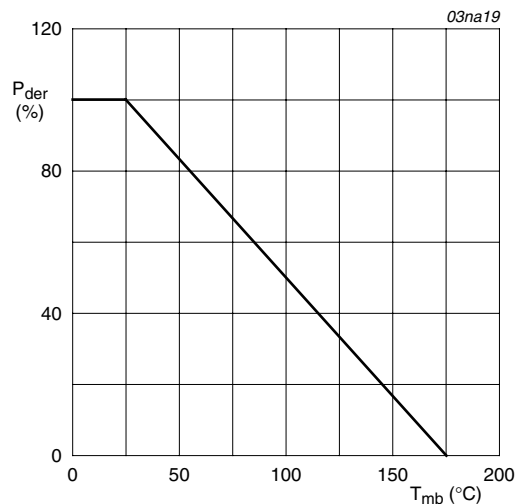
Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C		-	40	V
V _{DGR}	drain-gate voltage	R _{GS} = 20 kΩ		-	40	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	T _{mb} = 25 °C; V _{GS} = 10 V; see Figure 2 ;	[1]	-	117	A
		see Figure 3 ;	[2]	-	75	A
		T _{mb} = 100 °C; V _{GS} = 10 V; see Figure 2 ;	[2]	-	75	A
I _{DM}	peak drain current	T _{mb} = 25 °C; t _p ≤ 10 μs; pulsed; see Figure 3		-	468	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 1		-	221	W
I _{GS(CL)}	gate-source clamping current	continuous		-	10	mA
		pulsed; t _p = 5 ms; δ = 0.01		-	50	mA
T _{stg}	storage temperature			-55	175	°C
T _j	junction temperature			-55	175	°C
Source-drain diode						
I _S	source current	T _{mb} = 25 °C;	[1]	-	117	A
			[2]	-	75	A
I _{SM}	peak source current	t _p ≤ 10 μs; pulsed; T _{mb} = 25 °C		-	468	A
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I _D = 75 A; V _{sup} ≤ 40 V; R _{GS} = 50 Ω; V _{GS} = 10 V; T _{j(init)} = 25 °C; unclamped		-	0.63	J
Electrostatic discharge						
V _{esd}	electrostatic discharge voltage	HBM; C = 100 pF; R = 1.5 kΩ		-	6	kV

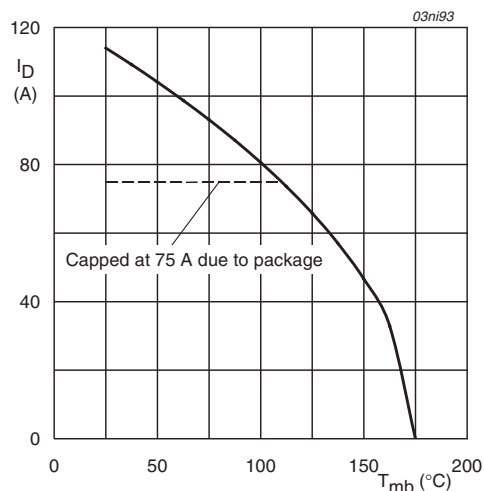
[1] Current is limited by power dissipation chip rating.

[2] Continuous current is limited by package.



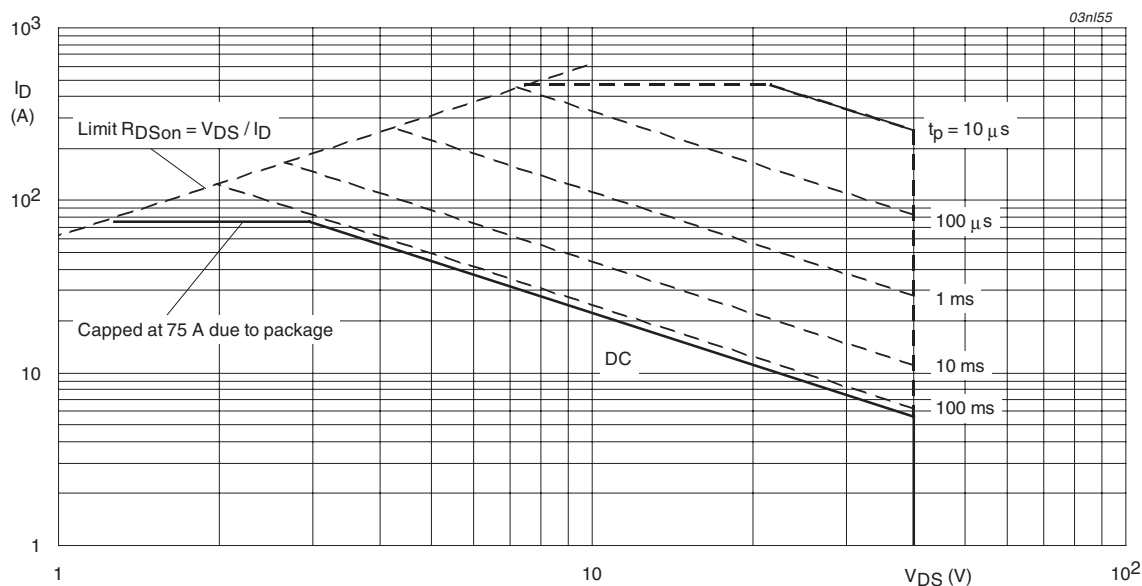
$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of mounting base temperature



$$V_{GS} \geq 10V$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature



$$T_{mb} = 25^{\circ}C; I_{DM} \text{ is single pulse}$$

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	minimum footprint; mounted on a printed-circuit board	-	50	-	K/W
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	-	0.68	K/W

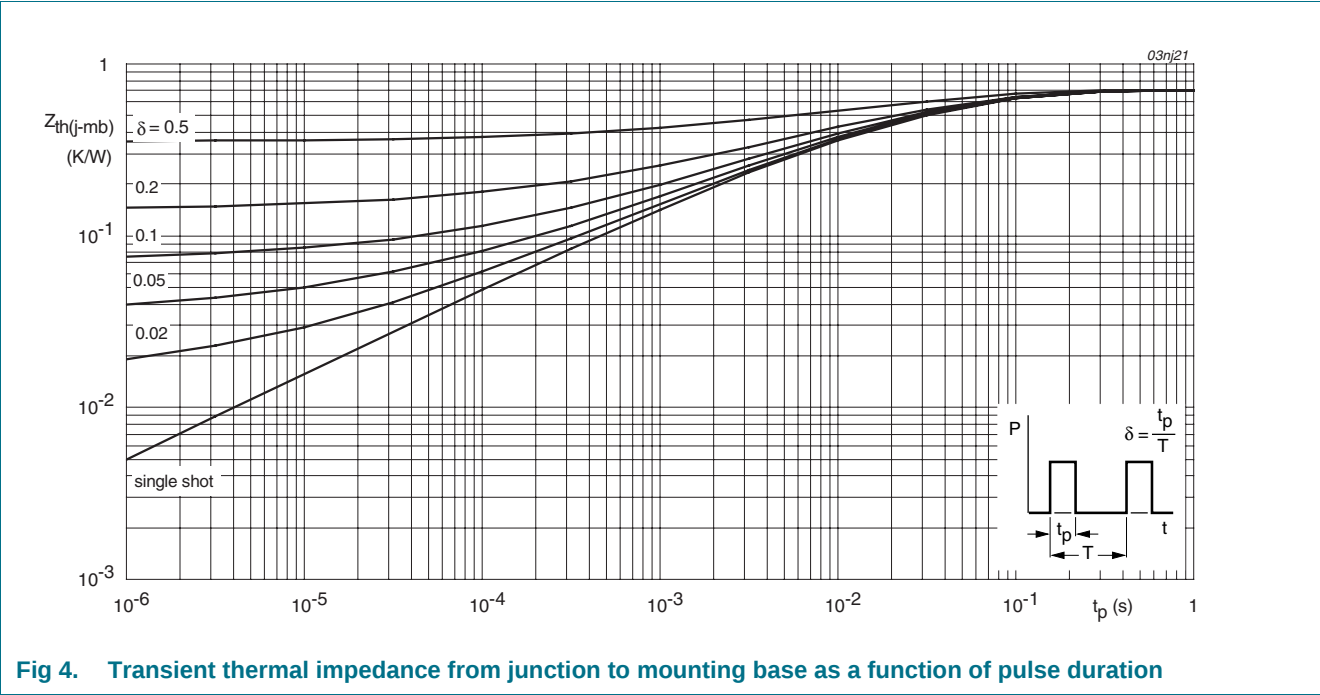


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

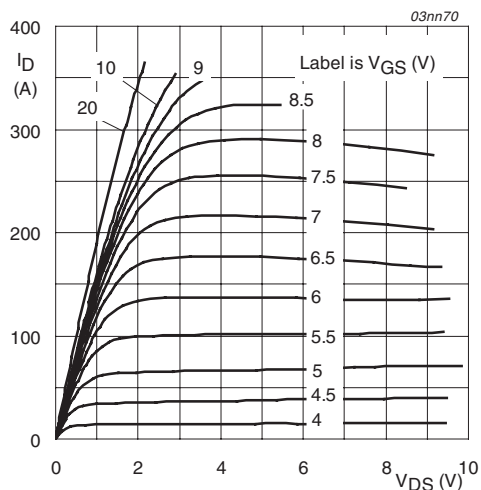
6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^{\circ}\text{C}$	40	-	-	V
		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ }^{\circ}\text{C}$	36	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ }^{\circ}\text{C};$ see Figure 9	2	3	4	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ }^{\circ}\text{C};$ see Figure 9	1	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ }^{\circ}\text{C};$ see Figure 9	-	-	4.4	V
I_{DSS}	drain leakage current	$V_{DS} = 40 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^{\circ}\text{C}$	-	0.1	10	μA
		$V_{DS} = 40 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 175 \text{ }^{\circ}\text{C}$	-	-	250	μA
$V_{(BR)GSS}$	gate-source breakdown voltage	$I_G = 1 \text{ mA}; V_{DS} = 0 \text{ V}; T_j > -55 \text{ }^{\circ}\text{C};$ $T_j < 175 \text{ }^{\circ}\text{C}$	20	22	-	V
		$I_G = -1 \text{ mA}; V_{DS} = 0 \text{ V}; T_j > -55 \text{ }^{\circ}\text{C};$ $T_j < 175 \text{ }^{\circ}\text{C}$	20	22	-	V
I_{GSS}	gate leakage current	$V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}; T_j = 25 \text{ }^{\circ}\text{C}$	-	22	300	nA
		$V_{DS} = 0 \text{ V}; V_{GS} = -10 \text{ V}; T_j = 25 \text{ }^{\circ}\text{C}$	-	22	300	nA
		$V_{DS} = 0 \text{ V}; V_{GS} = 10 \text{ V}; T_j = 175 \text{ }^{\circ}\text{C}$	-	-	10	μA
		$V_{DS} = 0 \text{ V}; V_{GS} = -10 \text{ V}; T_j = 175 \text{ }^{\circ}\text{C}$	-	-	10	μA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 50 \text{ A}; T_j = 25 \text{ }^{\circ}\text{C};$ see Figure 7 ; see Figure 8	-	6	8	m Ω
		$V_{GS} = 10 \text{ V}; I_D = 50 \text{ A}; T_j = 175 \text{ }^{\circ}\text{C};$ see Figure 7 ; see Figure 8	-	-	15.2	m Ω
$R_{(D-ISENSE)on}$	drain-ISENSE on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 10 \text{ mA}; T_j = 25 \text{ }^{\circ}\text{C}$	1.59	1.87	2.2	Ω
		$V_{GS} = 10 \text{ V}; I_D = 10 \text{ mA}; T_j = 175 \text{ }^{\circ}\text{C}$	3.02	3.55	4.18	Ω
I_D/I_{sense}	ratio of drain current to sense current	$V_{GS} > 10 \text{ V}; T_j > -55 \text{ }^{\circ}\text{C}; T_j < 175 \text{ }^{\circ}\text{C}$	450	500	550	
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	$I_D = 25 \text{ A}; V_{DS} = 32 \text{ V}; V_{GS} = 10 \text{ V};$ $T_j = 25 \text{ }^{\circ}\text{C};$ see Figure 14	-	78	84	nC
Q_{GS}	gate-source charge		-	14	16	nC
Q_{GD}	gate-drain charge		-	34	36	nC
C_{iss}	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ }^{\circ}\text{C};$ see Figure 12	-	2670	3140	pF
C_{oss}	output capacitance		-	900	1053	pF
C_{rss}	reverse transfer capacitance		-	560	653	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 30 \text{ V}; R_L = 1.2 \text{ } \Omega; V_{GS} = 10 \text{ V};$ $R_{G(ext)} 10 \text{ } \Omega; T_j = 25 \text{ }^{\circ}\text{C}$	-	19	-	ns
t_r	rise time		-	76	-	ns
$t_{d(off)}$	turn-off delay time		-	121	-	ns
t_f	fall time		-	122	-	ns

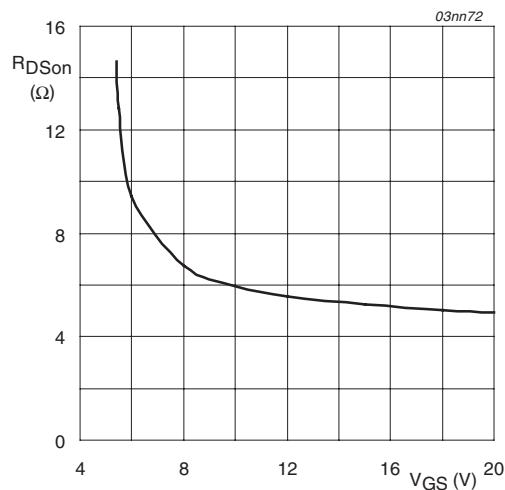
Table 6. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
L_D	internal drain inductance	from upper edge of drain mounting base to centre of die; $T_j = 25\text{ }^{\circ}\text{C}$	-	2.5	-	nH
L_S	internal source inductance	from source lead to source bond pad; $T_j = 25\text{ }^{\circ}\text{C}$; lead length 6 mm	-	7.5	-	nH
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 40\text{ A}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$; see Figure 17	-	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 20\text{ A}$; $di_S/dt = -100\text{ A}/\mu\text{s}$; $V_{GS} = -10\text{ V}$;	-	55	-	ns
Q_r	recovered charge	$V_{DS} = 30\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$	-	30	-	nC



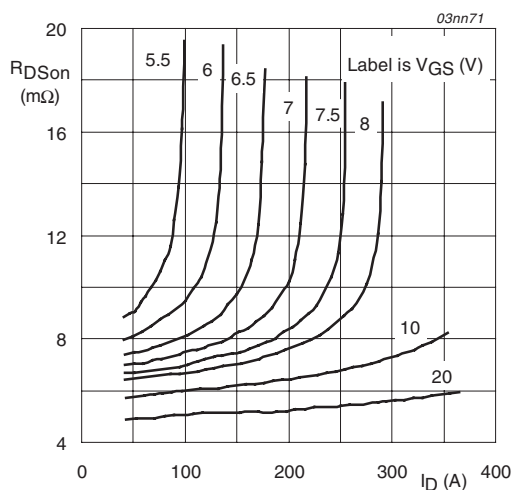
$$T_j = 25^{\circ}\text{C}; t_p = 300\mu\text{s}$$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



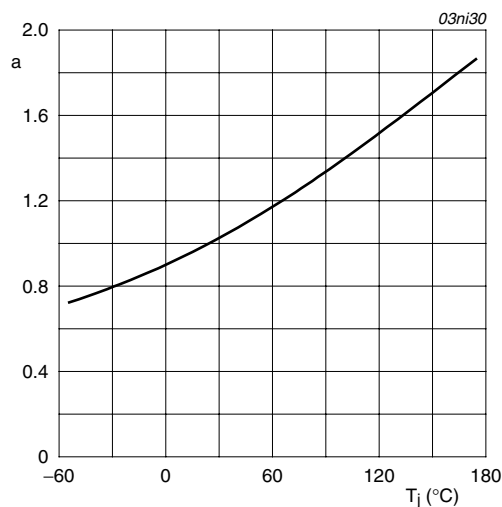
$$T_j = 25^{\circ}\text{C}; I_D = 50\text{A}$$

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



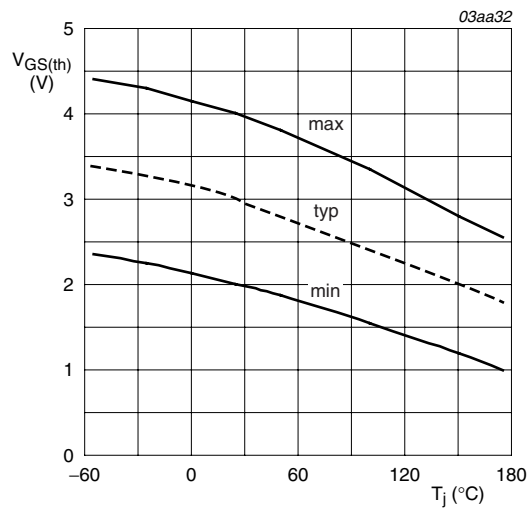
$$T_j = 25^{\circ}\text{C}; t_p = 300\mu\text{s}$$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values



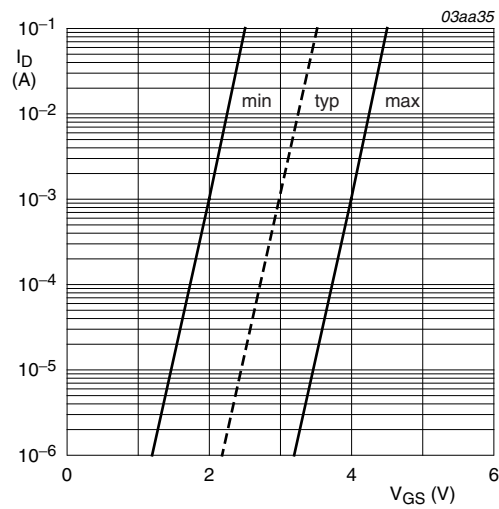
$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}\text{C})}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature



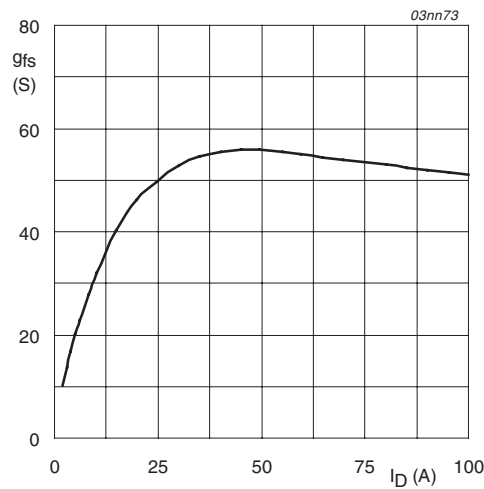
$I_D = 1\text{ mA}; V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature



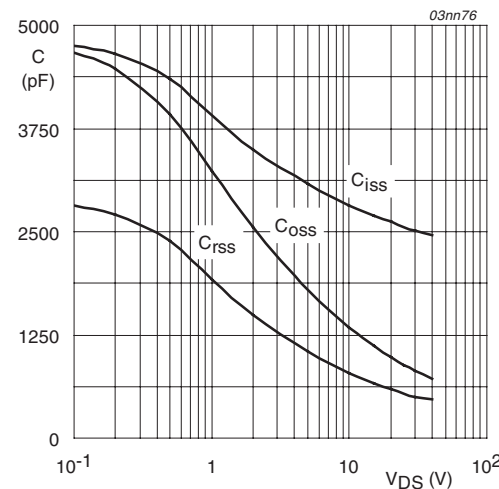
$T_j = 25\text{ °C}; V_{DS} = 5\text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage



$T_j = 25\text{ °C}; V_{DS} = 25\text{ V}$

Fig 11. Forward transconductance as a function of drain current; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

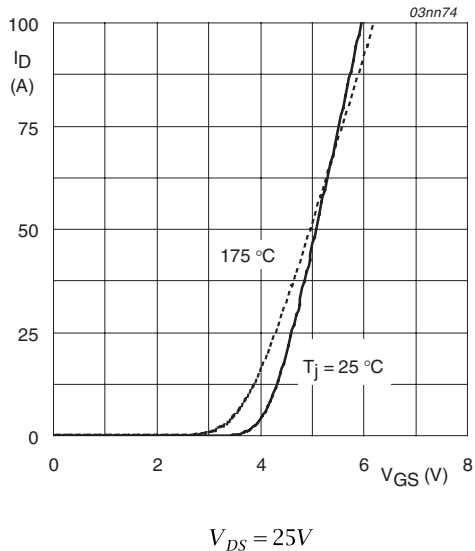


Fig 13. Transfer characteristics: drain current as a function of gate-source voltage; typical values

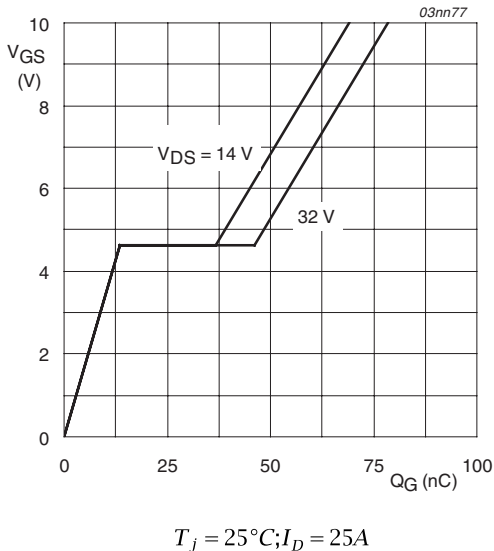


Fig 14. Gate-source voltage as a function of charge; typical values

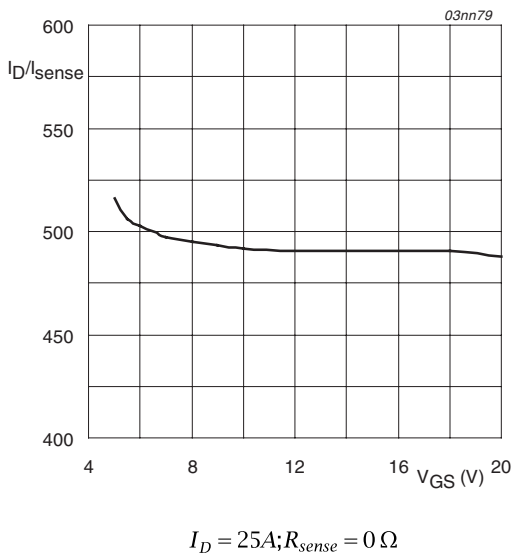


Fig 15. Drain-sense current ratio as a function of gate-source voltage; typical values

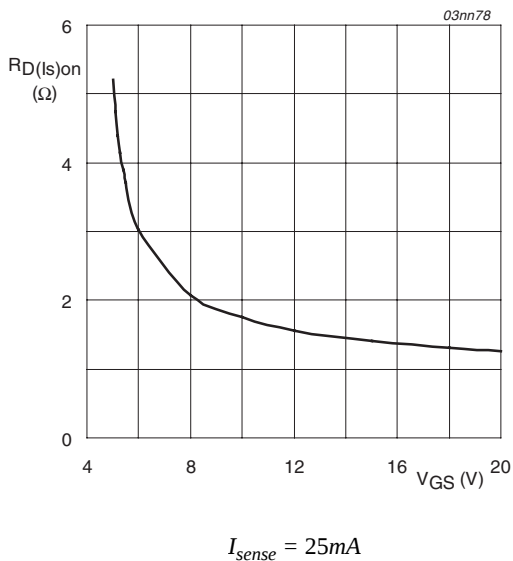
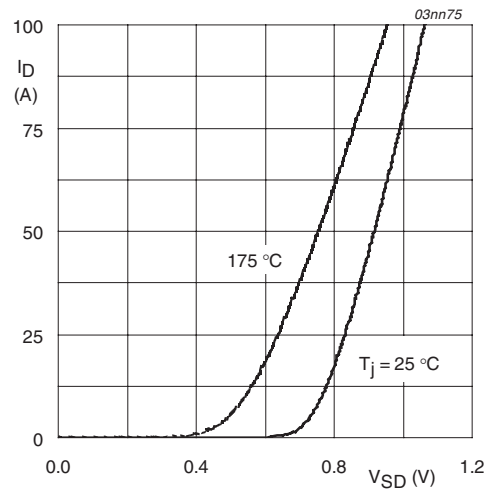


Fig 16. Drain-sense current on-state resistance as a function of gate-source voltage; typical values



$V_{GS} = 0V$

Fig 17. Drain current as a function of source-drain diode voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (D2PAK); 5 leads (one lead cropped)

SOT426

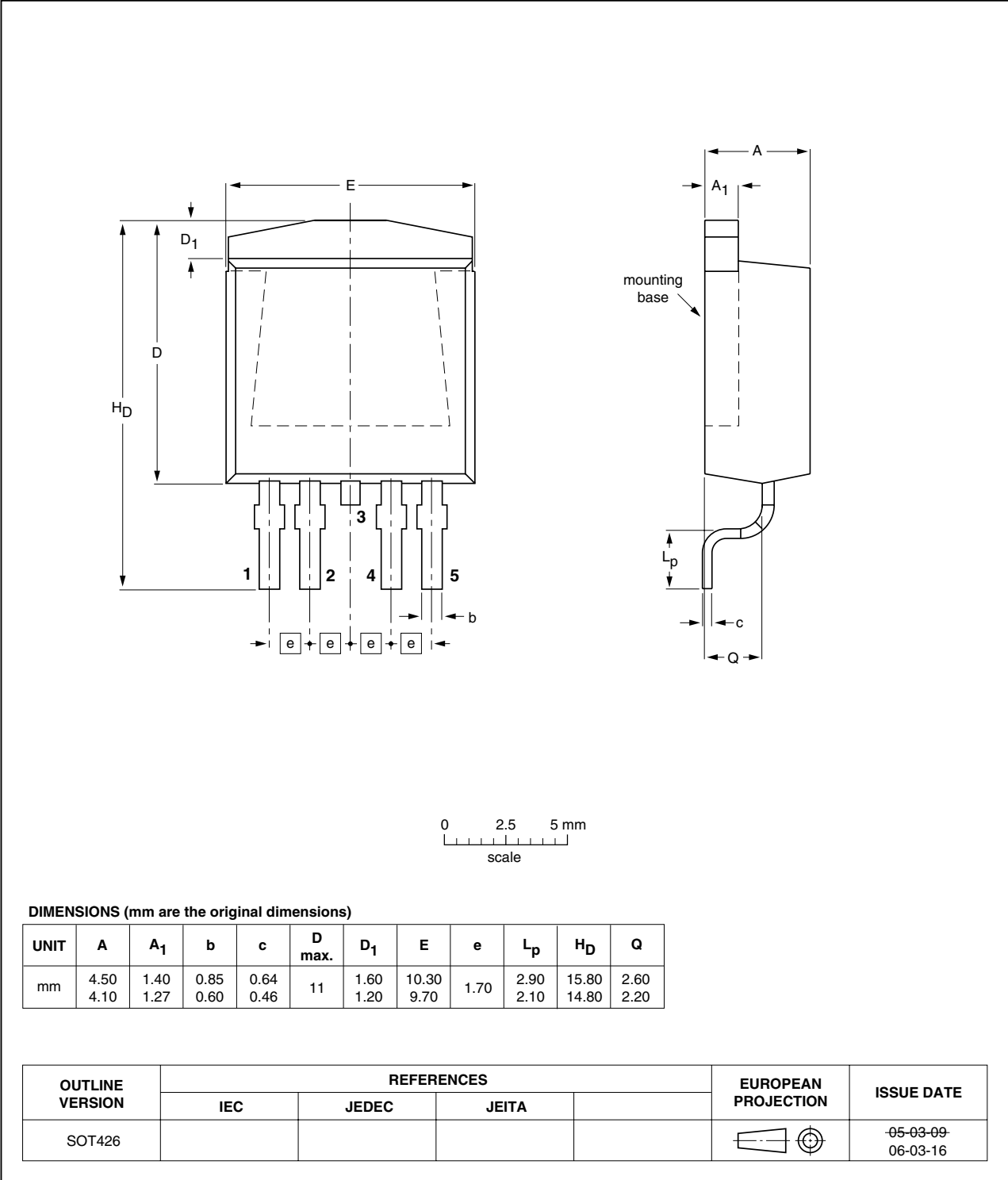


Fig 18. Package outline SOT426 (D2PAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK7108-40AIE_3	20090219	Product data sheet	-	BUK71_7908_40AIE-02
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Type number BUK7108-40AIE separated from data sheet BUK71_7908_40AIE-02.			
BUK71_7908_40AIE-02 (9397 750 12086)	20031024	Product data sheet	-	BUK71_7908_40AIE-01
BUK71_7908_40AIE-01 (9397 750 11695)	20030819	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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